

ISMP 2015

14th International Symposium
on Microelectronics and Packaging

October 13(Tue) -15(Thu), 2015
KINTEX Hall2, Seoul / Ilsan, Korea

<http://ismp2015.kmeps.or.kr>



Organized by :



The Korean Microelectronics and Packaging Society

Supported by :



Korea Semiconductor Industry Association

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INVITATION



General Chairman
of ISMP 2015
Ho Jung Chang, Ph.D

It is our pleasure to announce that the 14th International Symposium on Microelectronics and Packaging (ISMP 2015) will be held at KINTEX (Korea International Exhibition Center) convention center located at Seoul/Ilsan Korea during October 13-15 2015. This international conference is organized by KMEPS (the Korean Microelectronics and Packaging Society), and will address comprehensive coverage of recent advances in Materials, Processing, Simulation, Printed Electronics, Nano/Micro Joining Technology and Reliability of Electronic Packaging. The technical sessions for oral and poster presentations will be in parallel with the 17th International Semiconductor Exhibition (<http://www.sedex.org>) at KINTEX. The ISMP 2015 will provide an excellent opportunity for scientists and engineers of academic institutes and industries to discuss recent advances in electronic packaging technology and forecast new technological directions. We cordially invite you to submit abstracts for the conference, and look forward to welcoming you in Seoul, Korea.

SYMPOSIUM TOPICS

ISMP 2015 will include all fundamental and applied sciences and technologies related to the fields of electronic materials, devices, and packagings. Topics may include from, but are not limited to, the following areas:

- Electronic Materials and Processing
- Optoelectronic and Photonic Materials and Processing
- Advanced Packaging Technologies
- 3D Integration and Packaging
- LED Packaging and Applications
- MEMS Packaging and Applications
- Modeling, Simulation, Quality and Reliability of Electronic Components
- Nanomaterials and its Application Technology
- Micro/Nano Joining Technology
- Interconnection Materials and its Reliability
- IoT (Internet of Things), Sensor Devices and System
- Soldering and Surface Mount Technology
- Wearable and Stretchable Electronics
- Printed Electronics and Materials

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SPEAKERS (As of Mar. 31th, 2015)

Plenary Speakers



Choon Heung Lee
(President of AMKOR, Korea)



William Chen
(ASE, Taiwan)

Keynote Speakers



Akio Hirose
(Osaka University, Japan)



Bill Bader
(President of iNEMI, USA)



Rolf Aschenbrenner
(IZM Fraunhofer, Germany)



Chunqing Wang, China
(Harbin Institute of Technology)

Invited Speakers



N. N. Ekere
(Univ. of Wolverhampton, UK)



Mustafa Yavuz
(Univ. of Waterloo, Canada)

ABSTRACT SUBMISSION

You are invited to submit a 300-word abstract via ISMP 2015 website (<http://ismp2015.kmeps.or.kr>) including title, authors, affiliations, address and corresponding author (refer to abstract template) by May 31, 2015 for oral and poster presentations. Acknowledgement of your abstract submission will be sent to the presenting/corresponding authors' email addresses by July 15, 2015.

PAPER PUBLICATION

Authors whose abstracts are accepted will be requested to submit full manuscript by August 15, 2015 (manuscript submission is not mandatory). After peer review, all accepted papers will be published in following several leading SCI(E) and KCI journals.

- Soldering and Surface Mount Technology (SCIE) /
- Materials Transactions (SCI) / · Journal of Nanoelectronics and Optoelectronics (SCIE)
- Nanoscience and Nanotechnology Letters (SCIE) / · Journal of Microelectronics and Packaging Society (KCI)

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IMPORTANT DATES

Submission of Abstract : May 31, 2015
Notification of Acceptance : July 15, 2015
Pre-registration : August 15, 2015
Submission of Final Manuscript : August 15, 2015
Conference : October 13-15, 2015

Please submit the abstract via ISMP2015 website (<http://ismp2015.kmeps.or.kr>) and you can find your submission of the abstract at the site.

REGISTRATION

Category	Pre-Registration		On-site Registration	
	Overseas	Domestic	Overseas	Domestic
Regular	USD 450	KRW 450,000	USD 550	KRW 550,000
Student	USD 200	KRW 200,000	USD 300	KRW 300,000
Banquet	USD 100 / KRW 100,000 (for student and accompanying person registration)			

** Registration fee includes symposium program book with USB abstract proceeding, welcome party and luncheon coupons and free entrance ticket for the Korea Electronic Exhibition Show.

WELCOME PARTY

DATE : OCTOBER 13, 6 PM
VENUE : KINTEX

BANQUET

DATE : OCTOBER 14, 7 PM
VENUE : STANFORD HOTEL (<http://www.stanfordseoul.com/seoul>)

ACCOMMODATIONS



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+82-2-6016-0001

<http://www.stanfordseoul.com>



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CONTACT

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CONFERENCE LANGUAGE

The official language of the conference is English

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SPONSORSHIP for ISMP 2015

The conference organizers are seeking large spectrum of sponsorship and industrial support for ISMP 2015. The organizers expect a sponsorship offer at least 2 months ahead of the ISMP 2015. When you select a level of sponsorship, please indicate in the following Sponsorship Form the level of support.

SPONSOR FORM

Our company is pleased to support the ISMP 2015 by a sponsorship grant at the level indicated below.

Sponsoring company _____

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Please indicate the sponsorship level :

DIAMOND Sponsorship

\$10,000 (KRW 10,000,000) []

- Welcome address during Banquet
- 5 free conference passes
- Full-page advertising on the inside of the conference program.

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\$5,000 (KRW 5,000,000) []

- 3 free conference passes
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GOLD Sponsorship

\$3,000 (KRW 3,000,000) []

- 2 free conference passes
- Half-page advertising on the inside of the conference program.

SILVER Sponsorship

\$2,000 (KRW 2,000,000) []

- 1 free conference passes
- Half-page advertising on the inside of the conference program.

COMMON Sponsorship Benefits

- Logo at conference web site and link to the sponsor site
- Logo on the cover page of conference proceedings
- Company information, brochures, or other materials distributed to attendees

Contact Information: Ms. So-Yoon Park (KMEPS)

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ISMP 2015 Venue (KINTEX) Daehwa-dong, Ilsanseo-gu, Goyang-si, Gyeonggi-do, <http://www.kintex.com>



The Korea International Exhibition Center (KINTEX) is a brand new convention center located within 45 minutes from Seoul's downtown and showcases heavy industry products. As the largest exhibition center in Korea, KINTEX offers 5 exhibition halls and 23 meeting rooms in the space of 53,975m². Since its opening in April 2005, KINTEX has undergone the first of three expansion constructions, and is currently going through the second phase. When completed in September 2011, the expansion will add 53,975m² of exhibition space with world-class meeting facilities, placing KINTEX at the forefront of globalization and economic development in Korea.

i-SEDEX 2015

International Semiconductor Exhibition

OCTOBER 14-16
KINTEX KOREA



Device	Dram/Flash Memory, MCP, Memory module AP, MPU/MCU, DSP, DDI, PMIC, RFIC SoC etc. Foundries/Packaging Service, RFIDTag, Smart Card, Sensor, MEMS etc., Flat Panel Display (LCD, PDP, Organic EL, Etc)
Equipment Manufactures	Process Equipment, Assembly Equipment Test Equipment, Systems, SoC Test Systems etc. Inspection & Measurement Equipment General Equipment, Flat Panel Display Equipment
Factory Facility	Air Filtering, Clean Rooms, Flow Process Control, etc.
Materials	Materials of Assembly, Chemicals & Solids, Gases, FPD, Wafer Substrate
Components & Parts	Process Equipment, Sub System Parts
System & Software	FPGA/PLD, Wireless Communication, Interface Technology, Embedded Board Computer, CAD, Package Simulation, Test Program etc.

CONTACT i-SEDEX

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